

Data Sheet

ADG1611/ADG1612/ADG1613

FEATURES

- 1 Ω typical on resistance**
- 0.2 Ω on resistance flatness**
- ±3.3 V to ±8 V dual-supply operation**
- 3.3 V to 16 V single-supply operation**
- No V_L supply required**
- 3 V logic-compatible inputs**
- Rail-to-rail operation**
- Continuous current per channel**
- LFCSP package: 280 mA**
- TSSOP package: 175 mA**
- 16-lead TSSOP and 16-lead, 4 mm × 4 mm LFCSP**

APPLICATIONS

- Communication systems**
- Medical systems**
- Audio signal routing**
- Video signal routing**
- Automatic test equipment**
- Data acquisition systems**
- Battery-powered systems**
- Sample-and-hold systems**
- Relay replacements**

GENERAL DESCRIPTION

The ADG1611/ADG1612/ADG1613 contain four independent single-pole/single-throw (SPST) switches. The ADG1611 and ADG1612 differ only in that the digital control logic is inverted. The ADG1611 switches are turned on with Logic 0 on the appropriate control input, while Logic 1 is required for the ADG1612 switches. The ADG1613 has two switches with digital control logic similar to that of the ADG1611; the logic is inverted on the other two switches. Each switch conducts equally well in both directions when on and has an input signal range that extends to the supplies. In the off condition, signal levels up to the supplies are blocked.

The ADG1613 exhibits break-before-make switching action for use in multiplexer applications. Inherent in the design is the low charge injection for minimum transients when switching the digital inputs.

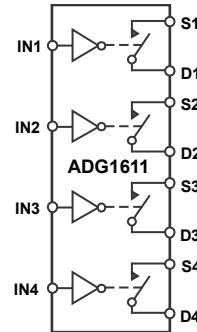
The ultralow on resistance of these switches make them ideal solutions for data acquisition and gain switching applications where low on resistance and distortion is critical. The on resistance profile is very flat over the full analog input range, ensuring excellent linearity and low distortion when switching audio signals.

The CMOS construction ensures ultralow power dissipation, making them ideally suited for portable and battery-powered instruments.

Rev. B

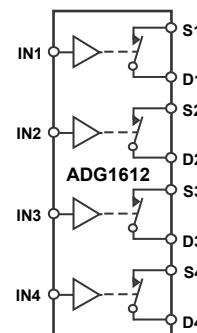
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FUNCTIONAL BLOCK DIAGRAMS



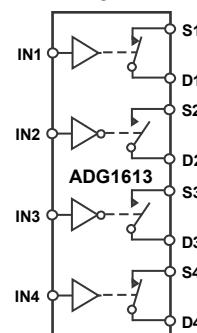
NOTES
1. SWITCHES SHOWN FOR A LOGIC 1 INPUT.
07981-001

Figure 1.



NOTES
1. SWITCHES SHOWN FOR A LOGIC 1 INPUT.
07981-033

Figure 2.



NOTES
1. SWITCHES SHOWN FOR A LOGIC 1 INPUT.
07981-034

Figure 3.

PRODUCT HIGHLIGHTS

1. 1.6Ω maximum on resistance over temperature.
2. Minimum distortion: THD + N = 0.007%.
3. 3 V logic-compatible digital inputs: $V_{INH} = 2.0$ V, $V_{INL} = 0.8$ V.
4. No V_L logic power supply required.
5. Ultralow power dissipation: <16 nW.
6. 16-lead TSSOP and 16-lead, 4 mm × 4 mm LFCSP.

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REVISION HISTORY

3/12—Rev. A to Rev. B

Changes to Figure 16..... 11

8/09—Rev. 0 to Rev. A

Changes to On Resistance (R_{ON}) Parameter, On Resistance Match Between Channels (ΔR_{ON}) Parameter, and On Resistance Flatness (R_{FLATON}) Parameter, Table 4

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Changes to Figure 7 Caption..... 10

1/09—Revision 0: Initial Version

SPECIFICATIONS**±5 V DUAL SUPPLY**

$V_{DD} = +5 \text{ V} \pm 10\%$, $V_{SS} = -5 \text{ V} \pm 10\%$, GND = 0 V, unless otherwise noted.

Table 1.

Parameter	25°C	-40°C to +85°C	-40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			V_{DD} to V_{SS}	V	
On Resistance (R_{ON})	1	1.2	1.4	Ω typ	$V_S = \pm 4.5 \text{ V}$, $I_S = -10 \text{ mA}$; see Figure 24
On Resistance Match Between Channels (ΔR_{ON})	0.04	0.08	0.09	Ω max	$V_{DD} = \pm 4.5 \text{ V}$, $V_{SS} = \pm 4.5 \text{ V}$
On Resistance Flatness ($R_{FLATNESS}$)	0.2	0.25	0.29	Ω typ	$V_S = \pm 4.5 \text{ V}$, $I_S = -10 \text{ mA}$
			0.1	Ω max	
On Resistance Flatness ($R_{FLATNESS}$)	0.25	0.25	0.34	Ω typ	$V_S = \pm 4.5 \text{ V}$, $I_S = -10 \text{ mA}$
			0.34	Ω max	
LEAKAGE CURRENTS					
Source Off Leakage, I_S (Off)	± 0.1			nA typ	$V_{DD} = +5.5 \text{ V}$, $V_{SS} = -5.5 \text{ V}$
Drain Off Leakage, I_D (Off)	± 0.3	± 1	± 6	nA max	$V_S = \pm 4.5 \text{ V}$, $V_D = \mp 4.5 \text{ V}$; see Figure 25
Channel On Leakage, I_D , I_S (On)	± 0.1	± 0.3	± 1	nA typ	$V_S = \pm 4.5 \text{ V}$, $V_D = \mp 4.5 \text{ V}$; see Figure 25
	± 0.2	± 0.2	± 6	nA max	
	± 0.4	± 1.5	± 10	nA typ	$V_S = V_D = \pm 4.5 \text{ V}$; see Figure 26
				nA max	
DIGITAL INPUTS					
Input High Voltage, V_{INH}			2.0	V min	
Input Low Voltage, V_{INL}			0.8	V max	
Input Current, I_{INL} or I_{INH}	+0.005		± 0.1	μA typ	$V_{IN} = V_{GND}$ or V_{DD}
			± 0.1	μA max	
Digital Input Capacitance, C_{IN}	5			pF typ	
DYNAMIC CHARACTERISTICS¹					
t_{ON}	165			ns typ	$R_L = 300 \Omega$, $C_L = 35 \text{ pF}$
	212	253	285	ns max	$V_S = 2.5 \text{ V}$; see Figure 31
t_{OFF}	105			ns typ	$R_L = 300 \Omega$, $C_L = 35 \text{ pF}$
	137	150	159	ns max	$V_S = 2.5 \text{ V}$; see Figure 31
Break-Before-Make Time Delay, t_D (ADG1613 Only)	25		ns typ	$R_L = 300 \Omega$, $C_L = 35 \text{ pF}$	
		20	ns min	$V_{S1} = V_{S2} = 2.5 \text{ V}$; see Figure 32	
Charge Injection	140		pC typ	$V_S = 0 \text{ V}$, $R_S = 0 \Omega$, $C_L = 1 \text{ nF}$; see Figure 33	
Off Isolation	70		dB typ	$R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 1 \text{ MHz}$; see Figure 27	
Channel-to-Channel Crosstalk	110		dB typ	$R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 1 \text{ MHz}$; see Figure 28	
Total Harmonic Distortion + Noise (THD + N)	0.007		% typ	$R_L = 110 \Omega$, 5 V p-p, $f = 20 \text{ Hz}$ to 20 kHz ; see Figure 30	
-3 dB Bandwidth	42		MHz typ	$R_L = 50 \Omega$, $C_L = 5 \text{ pF}$; see Figure 29	
C_S (Off)	63		pF typ	$V_S = 0 \text{ V}$, $f = 1 \text{ MHz}$	
C_D (Off)	63		pF typ	$V_S = 0 \text{ V}$, $f = 1 \text{ MHz}$	
C_D , C_S (On)	154		pF typ	$V_S = 0 \text{ V}$, $f = 1 \text{ MHz}$	
POWER REQUIREMENTS					
I_{DD}	0.001			μA typ	$V_{DD} = +5.5 \text{ V}$, $V_{SS} = -5.5 \text{ V}$
		1.0		μA max	Digital inputs = 0 V or V_{DD}
V_{DD}/V_{SS}			$\pm 3.3/\pm 8$	V min/max	

¹ Guaranteed by design, not subject to production test.

12 V SINGLE SUPPLY

$V_{DD} = 12 \text{ V} \pm 10\%$, $V_{SS} = 0 \text{ V}$, GND = 0 V, unless otherwise noted.

Table 2.

Parameter	25°C	-40°C to +85°C	-40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V_{DD}	V	
On Resistance (R_{ON})	0.95			Ω typ	$V_S = 0 \text{ V}$ to 10 V, $I_S = -10 \text{ mA}$; see Figure 24
	1.1	1.25	1.45	Ω max	$V_{DD} = 10.8 \text{ V}$, $V_{SS} = 0 \text{ V}$
On Resistance Match Between Channels (ΔR_{ON})	0.03			Ω typ	$V_S = 0 \text{ V}$ to 10 V, $I_S = -10 \text{ mA}$
	0.06	0.7	0.08	Ω max	
On Resistance Flatness ($R_{FLAT(ON)}$)	0.2			Ω typ	$V_S = 0 \text{ V}$ to 10 V, $I_S = -10 \text{ mA}$
	0.23	0.27	0.32	Ω max	
LEAKAGE CURRENTS					
Source Off Leakage, I_S (Off)	± 0.1			nA typ	$V_{DD} = 13.2 \text{ V}$, $V_{SS} = 0 \text{ V}$
	± 0.3	± 1	± 6	nA max	$V_S = 1 \text{ V}/10 \text{ V}$, $V_S = 10 \text{ V}/1 \text{ V}$, see Figure 25
Drain Off Leakage, I_D (Off)	± 0.1			nA typ	$V_S = 1 \text{ V}/10 \text{ V}$, $V_S = 10 \text{ V}/1 \text{ V}$ see Figure 25
	± 0.3	± 1	± 6	nA max	
Channel On Leakage, I_D , I_S (On)	± 0.2			nA typ	$V_S = V_D = 1 \text{ V}$ or 10 V; see Figure 26
	± 0.4	± 1.5	± 10	nA max	
DIGITAL INPUTS					
Input High Voltage, V_{INH}			2.0	V min	
Input Low Voltage, V_{INL}			0.8	V max	
Input Current, I_{INL} or I_{INH}	0.001		± 0.1	μA typ	
				μA max	
Digital Input Capacitance, C_{IN}	5			pF typ	
DYNAMIC CHARACTERISTICS ¹					
t_{ON}	125			ns typ	$R_L = 300 \Omega$, $C_L = 35 \text{ pF}$
	156	190	215	ns max	$V_S = 8 \text{ V}$; see Figure 31
t_{OFF}	75			ns typ	$R_L = 300 \Omega$, $C_L = 35 \text{ pF}$
	87	93	99	ns max	$V_S = 8 \text{ V}$; see Figure 31
Break-Before-Make Time Delay, t_D (ADG1613 Only)	35		30	ns typ	$R_L = 300 \Omega$, $C_L = 35 \text{ pF}$
				ns min	$V_{S1} = V_{S2} = 8 \text{ V}$; see Figure 32
Charge Injection	170			pC typ	$V_S = 6 \text{ V}$, $R_S = 0 \Omega$, $C_L = 1 \text{ nF}$; see Figure 33
Off Isolation	70			dB typ	$R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 1 \text{ MHz}$; see Figure 27
Channel-to-Channel Crosstalk	110			dB typ	$R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 1 \text{ MHz}$; see Figure 28
Total Harmonic Distortion + Noise	0.012			% typ	$R_L = 110 \Omega$, 5 V p-p, $f = 20 \text{ Hz}$ to 20 kHz; see Figure 30
-3 dB Bandwidth	38			MHz typ	$R_L = 50 \Omega$, $C_L = 5 \text{ pF}$; see Figure 29
C_S (Off)	60			pF typ	$V_S = 6 \text{ V}$, $f = 1 \text{ MHz}$
C_D (Off)	60			pF typ	$V_S = 6 \text{ V}$, $f = 1 \text{ MHz}$
C_D , C_S (On)	154			pF typ	$V_S = 6 \text{ V}$, $f = 1 \text{ MHz}$
POWER REQUIREMENTS					
I_{DD}	0.001			μA typ	$V_{DD} = 12 \text{ V}$
			1	μA max	Digital inputs = 0 V or V_{DD}
I_{DD}	320		480	μA typ	Digital inputs = 5 V
			3.3/16	μA max	
V_{DD}				V min/max	

¹ Guaranteed by design, not subject to production test.

5 V SINGLE SUPPLY

$V_{DD} = 5 \text{ V} \pm 10\%$, $V_{SS} = 0 \text{ V}$, GND = 0 V, unless otherwise noted.

Table 3.

Parameter	25°C	-40°C to +85°C	-40°C to 125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V_{DD}	V	
On Resistance (R_{ON})	1.7			Ω typ	$V_S = 0 \text{ V}$ to 4.5 V, $I_S = -10 \text{ mA}$; see Figure 24
	2.15	2.4	2.7	Ω max	$V_{DD} = 4.5 \text{ V}$, $V_{SS} = 0 \text{ V}$
On Resistance Match Between Channels (ΔR_{ON})	0.05			Ω typ	$V_S = 0 \text{ V}$ to 4.5 V, $I_S = -10 \text{ mA}$
	0.09	0.12	0.15	Ω max	
On Resistance Flatness ($R_{FLATNESS}$)	0.4			Ω typ	$V_S = 0 \text{ V}$ to 4.5 V, $I_S = -10 \text{ mA}$
	0.53	0.55	0.6	Ω max	
LEAKAGE CURRENTS					
Source Off Leakage, I_S (Off)	± 0.05			nA typ	$V_{DD} = 5.5 \text{ V}$, $V_{SS} = 0 \text{ V}$
	± 0.3	± 1	± 6	nA max	$V_S = 1 \text{ V}/4.5 \text{ V}$, $V_D = 4.5 \text{ V}/1 \text{ V}$; see Figure 25
Drain Off Leakage, I_D (Off)	± 0.05			nA typ	$V_S = 1 \text{ V}/4.5 \text{ V}$, $V_D = 4.5 \text{ V}/1 \text{ V}$; see Figure 25
	± 0.3	± 1	± 6	nA max	
Channel On Leakage, I_D , I_S (On)	± 0.15			nA typ	$V_S = V_D = 1 \text{ V}$ or 4.5 V; see Figure 26
	± 0.4	± 1.5	± 10	nA max	
DIGITAL INPUTS					
Input High Voltage, V_{INH}		2.0		V min	
Input Low Voltage, V_{INL}		0.8		V max	
Input Current, I_{INL} or I_{INH}	0.001		± 0.1	μA typ	$V_{IN} = V_{GND}$ or V_{DD}
Digital Input Capacitance, C_{IN}	5			μA max	
				pF typ	
DYNAMIC CHARACTERISTICS ¹					
t_{ON}	215			ns typ	$R_L = 300 \Omega$, $C_L = 35 \text{ pF}$
	279	334	376	ns max	$V_S = 2.5 \text{ V}$; see Figure 31
t_{OFF}	115			ns typ	$R_L = 300 \Omega$, $C_L = 35 \text{ pF}$
	150	169	180	ns max	$V_S = 2.5 \text{ V}$; see Figure 31
Break-Before-Make Time Delay, t_D (ADG1613 Only)	35		25	ns typ	$R_L = 300 \Omega$, $C_L = 35 \text{ pF}$
				ns min	$V_{S1} = V_{S2} = 2.5 \text{ V}$; see Figure 32
Charge Injection	80			pC typ	$V_S = 0 \text{ V}$, $R_S = 0 \Omega$, $C_L = 1 \text{ nF}$; see Figure 33
Off Isolation	70			dB typ	$R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 100 \text{ kHz}$; see Figure 27
Channel-to-Channel Crosstalk	110			dB typ	$R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 100 \text{ kHz}$; see Figure 28
Total Harmonic Distortion + Noise	0.093			% typ	$R_L = 110 \Omega$, $f = 20 \text{ Hz}$ to 20 kHz, $V_S = 3.5 \text{ V}$ p-p; see Figure 30
-3 dB Bandwidth	42			MHz typ	$R_L = 50 \Omega$, $C_L = 5 \text{ pF}$; see Figure 29
C_S (Off)	72			pF typ	$V_S = 2.5 \text{ V}$, $f = 1 \text{ MHz}$
C_D (Off)	72			pF typ	$V_S = 2.5 \text{ V}$, $f = 1 \text{ MHz}$
C_D , C_S (On)	160			pF typ	$V_S = 2.5 \text{ V}$, $f = 1 \text{ MHz}$
POWER REQUIREMENTS					
I_{DD}	0.001		1	μA typ	$V_{DD} = 5.5 \text{ V}$
			3.3/16	μA max	Digital inputs = 0 V or V_{DD}
V_{DD}				V min/max	

¹ Guaranteed by design, not subject to production test.

3.3 V SINGLE SUPPLY

$V_{DD} = 3.3\text{ V}$, $V_{SS} = 0\text{ V}$, $GND = 0\text{ V}$, unless otherwise noted.

Table 4.

Parameter	25°C	-40°C to +85°C	-40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V_{DD}	V	
On Resistance (R_{ON})	3.2	3.4	3.6	Ω typ	$V_S = 0\text{ V}$ to V_{DD} , $I_S = -10\text{ mA}$, $V_{DD} = 3.3\text{ V}$, $V_{SS} = 0\text{ V}$; see Figure 24
On Resistance Match Between Channels (ΔR_{ON})	0.06	0.07	0.08	Ω typ	$V_S = 0\text{ V}$ to V_{DD} , $I_S = -10\text{ mA}$
On Resistance Flatness ($R_{FLAT(ON)}$)	1.2	1.3	1.4	Ω typ	$V_S = 0\text{ V}$ to V_{DD} , $I_S = -10\text{ mA}$
LEAKAGE CURRENTS					
Source Off Leakage, I_S (Off)	± 0.02			nA typ	$V_{DD} = 3.6\text{ V}$, $V_{SS} = 0\text{ V}$
	± 0.3	± 1	± 6	nA max	$V_S = 0.6\text{ V}/3\text{ V}$, $V_D = 3\text{ V}/0.6\text{ V}$; see Figure 25
Drain Off Leakage, I_D (Off)	± 0.02			nA typ	$V_S = 0.6\text{ V}/3\text{ V}$, $V_D = 3\text{ V}/0.6\text{ V}$; see Figure 25
	± 0.3	± 1	± 6	nA max	
Channel On Leakage, I_D , I_S (On)	± 0.1			nA typ	$V_S = V_D = 0.6\text{ V}$ or 3 V ; see Figure 26
	± 0.4	± 1.5	± 10	nA max	
DIGITAL INPUTS					
Input High Voltage, V_{INH}			2.0	V min	
Input Low Voltage, V_{INL}			0.8	V max	
Input Current, I_{INL} or I_{INH}	0.001		± 0.1	μA typ	$V_{IN} = V_{GND}$ or V_{DD}
Digital Input Capacitance, C_{IN}	3			μA max	
				pF typ	
DYNAMIC CHARACTERISTICS¹					
t_{ON}	350			ns typ	$R_L = 300\ \Omega$, $C_L = 35\ pF$
	493	556	603	ns max	$V_S = 1.5\text{ V}$; see Figure 31
t_{OFF}	190			ns typ	$R_L = 300\ \Omega$, $C_L = 35\ pF$
	263	286	300	ns max	$V_S = 1.5\text{ V}$; see Figure 31
Break-Before-Make Time Delay, t_D (ADG1613 Only)	25		18	ns typ	$R_L = 300\ \Omega$, $C_L = 35\ pF$
				ns min	$V_{S1} = V_{S2} = 1.5\text{ V}$; see Figure 32
Charge Injection	50			pC typ	$V_S = 1.5\text{ V}$, $R_S = 0\ \Omega$, $C_L = 1\ nF$; see Figure 33
Off Isolation	70			dB typ	$R_L = 50\ \Omega$, $C_L = 5\ pF$, $f = 100\ kHz$; see Figure 27
Channel-to-Channel Crosstalk	110			dB typ	$R_L = 50\ \Omega$, $C_L = 5\ pF$, $f = 100\ kHz$; see Figure 28
Total Harmonic Distortion + Noise	0.18			% typ	$R_L = 110\ \Omega$, $f = 20\ Hz$ to $20\ kHz$, $V_S = 2\text{ V}$ p-p; see Figure 30
-3 dB Bandwidth	52			MHz typ	$R_L = 50\ \Omega$, $C_L = 5\ pF$; see Figure 29
C_S (Off)	76			pF typ	$V_S = 1.5\text{ V}$, $f = 1\ MHz$
C_D (Off)	76			pF typ	$V_S = 1.5\text{ V}$, $f = 1\ MHz$
C_D , C_S (On)	160			pF typ	$V_S = 1.5\text{ V}$, $f = 1\ MHz$
POWER REQUIREMENTS					
I_{DD}	0.001	1.0	1.0	μA typ	$V_{DD} = 3.6\text{ V}$
			3.3/16	μA max	Digital inputs = 0 V or V_{DD}
V_{DD}				V min/max	

¹ Guaranteed by design, not subject to production test.

CONTINUOUS CURRENT PER CHANNEL, S OR D

Table 5.

Parameter	25°C	85°C	125°C	Unit
CONTINUOUS CURRENT, S OR D $V_{DD} = +5\text{ V}, V_{SS} = -5\text{ V}$ TSSOP ($\theta_{JA} = 150.4^\circ\text{C/W}$) LFCSP ($\theta_{JA} = 48.7^\circ\text{C/W}$)	175 280	119 175	70 95	mA maximum mA maximum
$V_{DD} = 12\text{ V}, V_{SS} = 0\text{ V}$ TSSOP ($\theta_{JA} = 150.4^\circ\text{C/W}$) LFCSP ($\theta_{JA} = 48.7^\circ\text{C/W}$)	206 336	135 203	84 108	mA maximum mA maximum
$V_{DD} = 5\text{ V}, V_{SS} = 0\text{ V}$ TSSOP ($\theta_{JA} = 150.4^\circ\text{C/W}$) LFCSP ($\theta_{JA} = 48.7^\circ\text{C/W}$)	140 220	91 140	63 84	mA maximum mA maximum
$V_{DD} = 3.3\text{ V}, V_{SS} = 0\text{ V}$ TSSOP ($\theta_{JA} = 150.4^\circ\text{C/W}$) LFCSP ($\theta_{JA} = 48.7^\circ\text{C/W}$)	140 228	98 150	70 91	mA maximum mA maximum

ABSOLUTE MAXIMUM RATINGS

T_A = 25°C, unless otherwise noted.

Table 6.

Parameter	Rating
V _{DD} to V _{SS}	18 V
V _{DD} to GND	-0.3 V to +18 V
V _{SS} to GND	+0.3 V to -18 V
Analog Inputs ¹	V _{SS} – 0.3 V to V _{DD} + 0.3 V or 30 mA, whichever occurs first
Digital Inputs ¹	GND – 0.3 V to V _{DD} + 0.3 V or 30 mA, whichever occurs first
Peak Current, S or D	630 mA (pulsed at 1 ms, 10% duty-cycle maximum)
Continuous Current, S or D ²	Data + 15%
Operating Temperature Range Industrial (Y Version)	-40°C to +125°C
Storage Temperature Range	-65°C to +150°C
Junction Temperature	150°C
16-Lead TSSOP, θ _{JA} Thermal Impedance (2-Layer Board)	150.4°C/W
16-Lead LFCSP, θ _{JA} Thermal Impedance (4-Layer Board)	48.7°C/W
Reflow Soldering Peak Temperature, Pb free	260°C

¹ Overvoltages at IN, S, or D are clamped by internal diodes. Current should be limited to the maximum ratings given.

² See Table 5.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION



ESD (electrostatic discharge) sensitive device.
Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

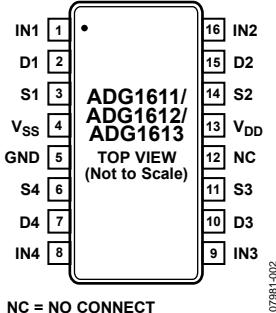
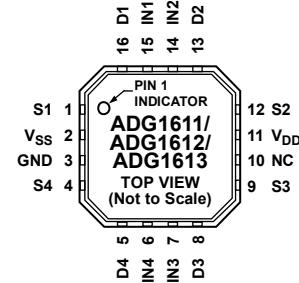


Figure 4. 16-Lead TSSOP Pin Configuration



NOTES
 1. NC = NO CONNECT.
 2. EXPOSED PAD TIED TO SUBSTRATE, V_{ss}.

Figure 5. 16-Lead LFCSP Pin Configuration

Table 7. Pin Function Descriptions

Pin No.		Mnemonic	Description
16-Lead TSSOP	16-Lead LFCSP		
1	15	IN1	Logic Control Input.
2	16	D1	Drain Terminal. This pin can be an input or output.
3	1	S1	Source Terminal. This pin can be an input or output.
4	2	V _{ss}	Most Negative Power Supply Potential.
5	3	GND	Ground (0 V) Reference.
6	4	S4	Source Terminal. This pin can be an input or output.
7	5	D4	Drain Terminal. This pin can be an input or output.
8	6	IN4	Logic Control Input.
9	7	IN3	Logic Control Input.
10	8	D3	Drain Terminal. This pin can be an input or output.
11	9	S3	Source Terminal. This pin can be an input or output.
12	10	NC	No Connection.
13	11	V _{dd}	Most Positive Power Supply Potential.
14	12	S2	Source Terminal. This pin can be an input or output.
15	13	D2	Drain Terminal. This pin can be an input or output.
16	14	IN2	Logic Control Input.
Not applicable	17 (EPAD)	EP (EPAD)	Exposed Pad. Tied to substrate, V _{ss} .

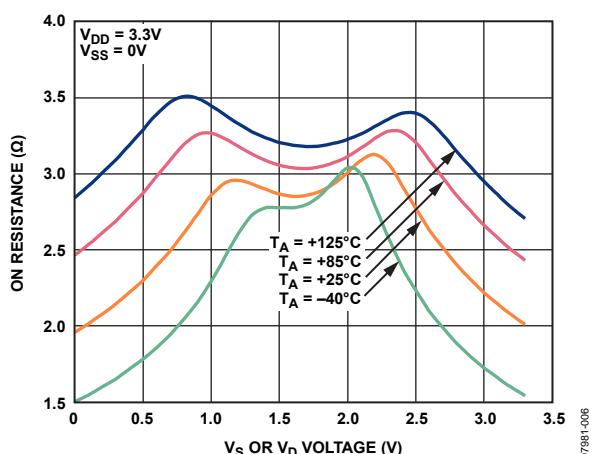
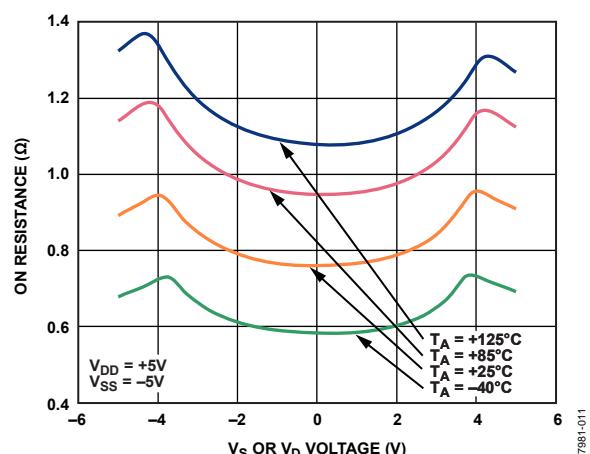
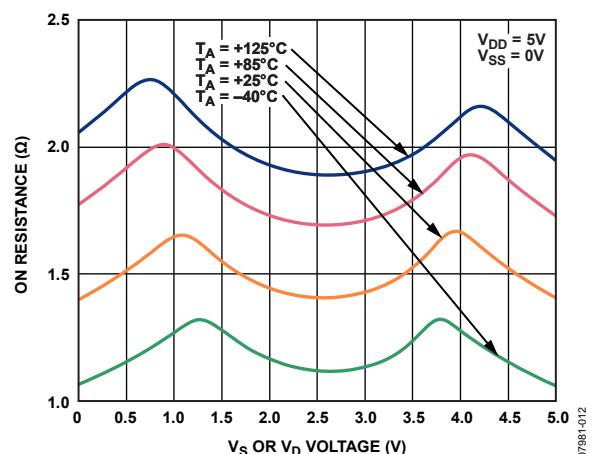
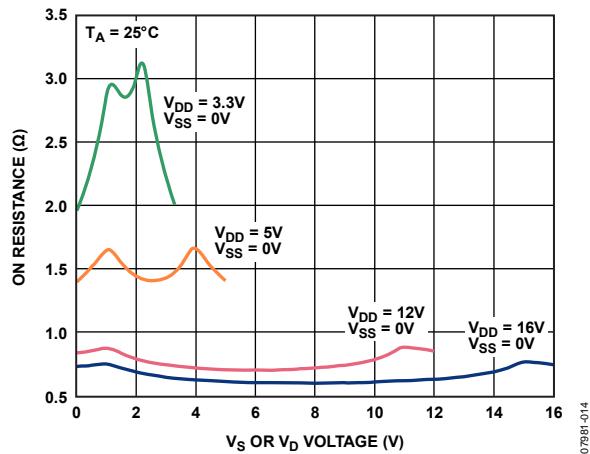
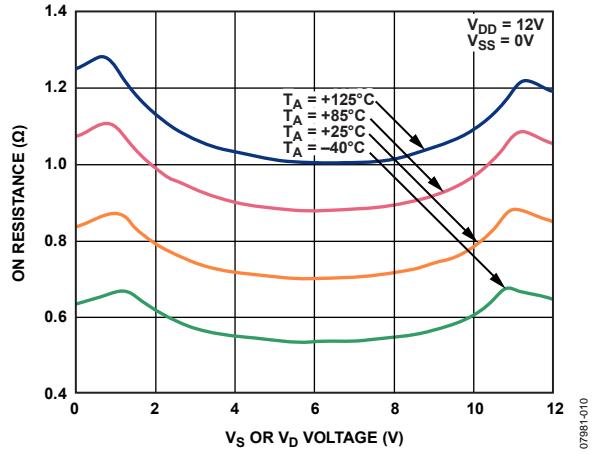
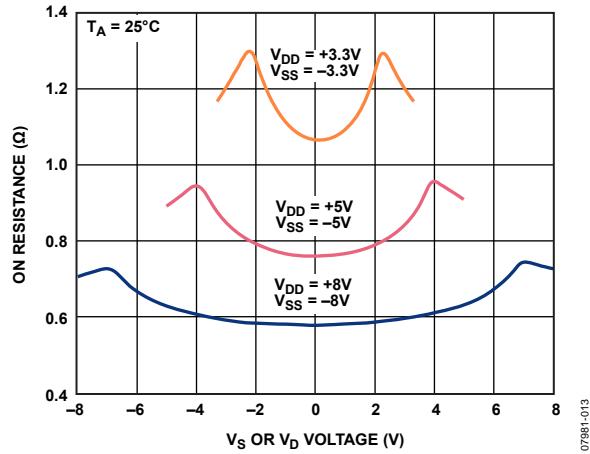
Table 8. ADG1611/ADG1612 Truth Table

ADG1611 INx	ADG1612 INx	Switch Condition
0	1	On
1	0	Off

Table 9. ADG1613 Truth Table

Logic (INx)	Switch 1, Switch 4	Switch 2, Switch 3
0	Off	On
1	On	Off

TYPICAL PERFORMANCE CHARACTERISTICS



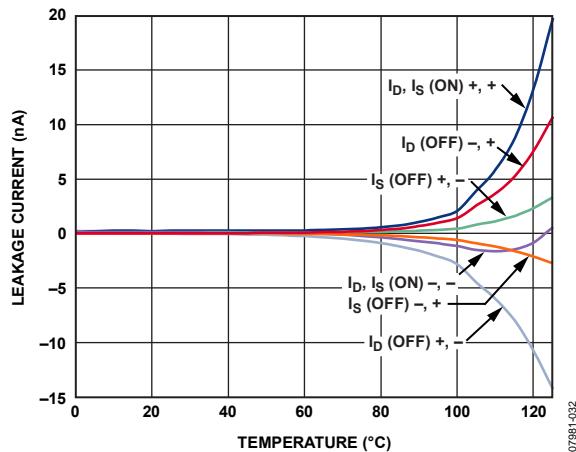
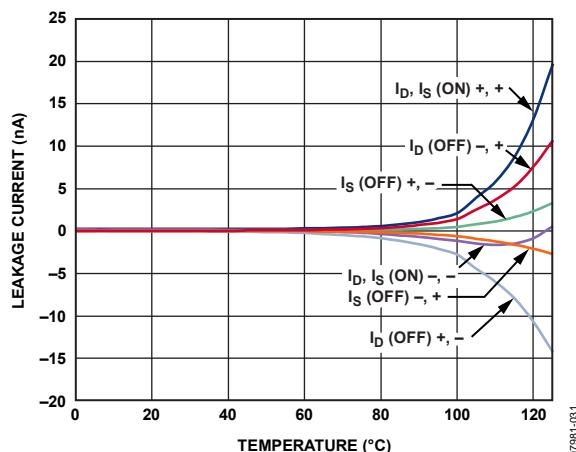
Figure 12. Leakage Currents as a Function of Temperature, ± 5 V Dual Supply

Figure 13. Leakage Currents as a Function of Temperature, 12 V Single Supply

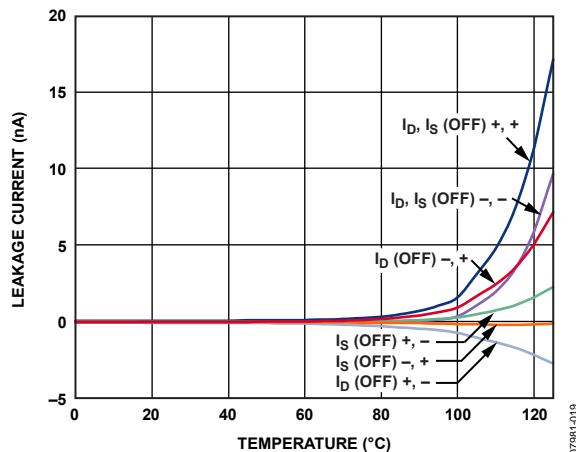


Figure 14. Leakage Currents as a Function of Temperature, 5 V Single Supply

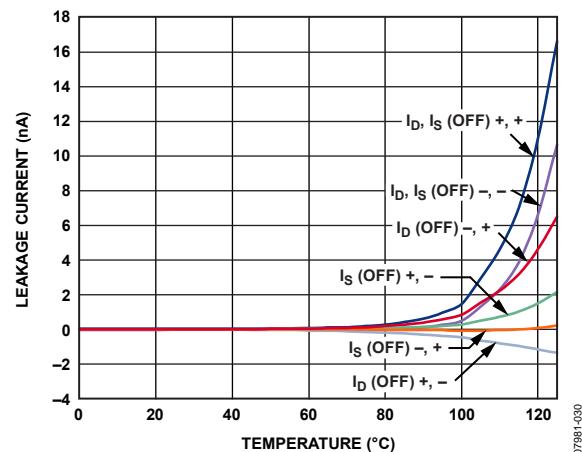
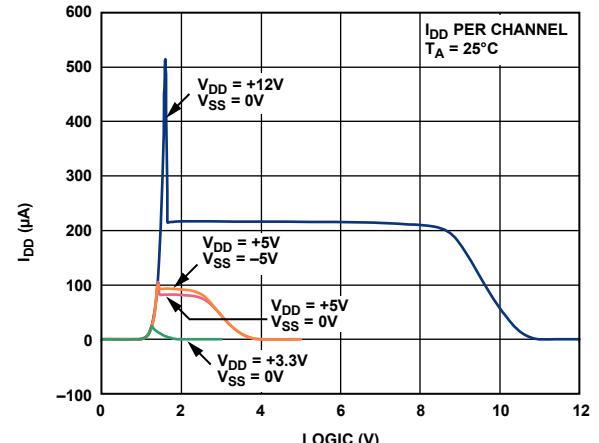
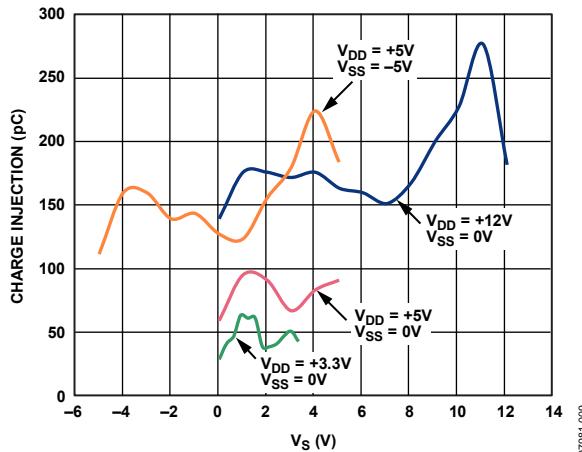


Figure 15. Leakage Currents as a Function of Temperature, 3.3 V Single Supply

Figure 16. I_{DD} vs. Logic LevelFigure 17. Charge Injection vs. Source Voltage (V_S)

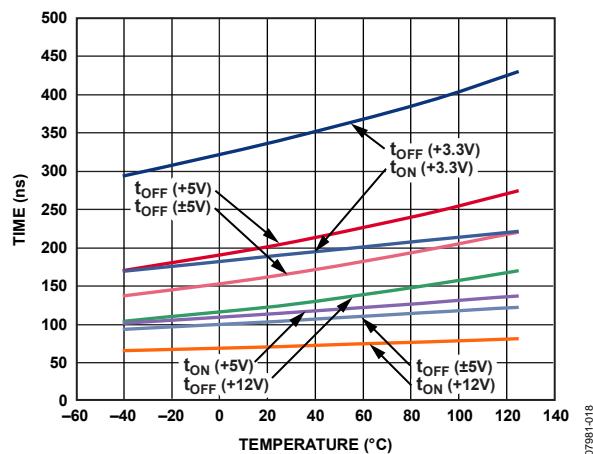
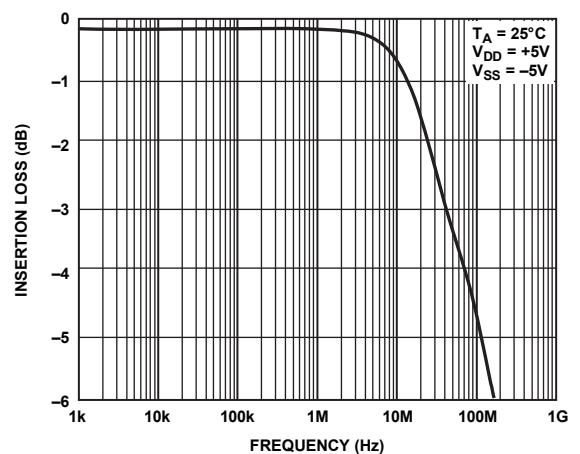
Figure 18. t_{ON}/t_{OFF} Times vs. Temperature

Figure 21. On Response vs. Frequency

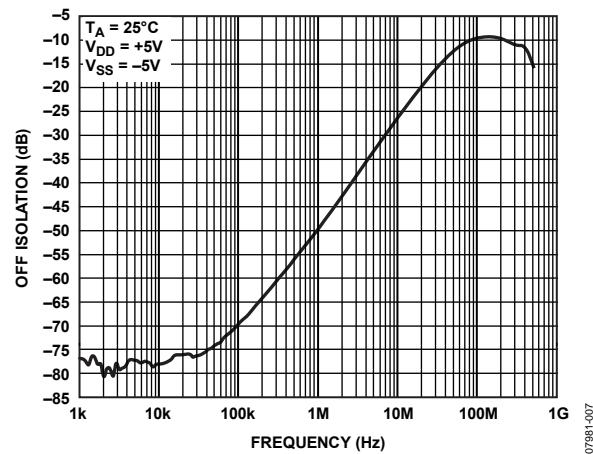


Figure 19. Off Isolation vs. Frequency

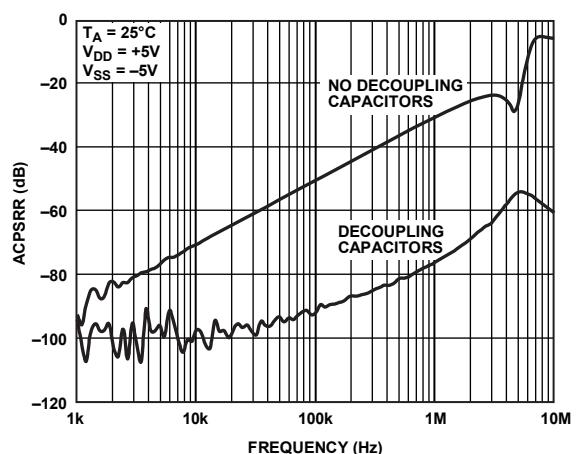


Figure 22. ACPSRR vs. Frequency

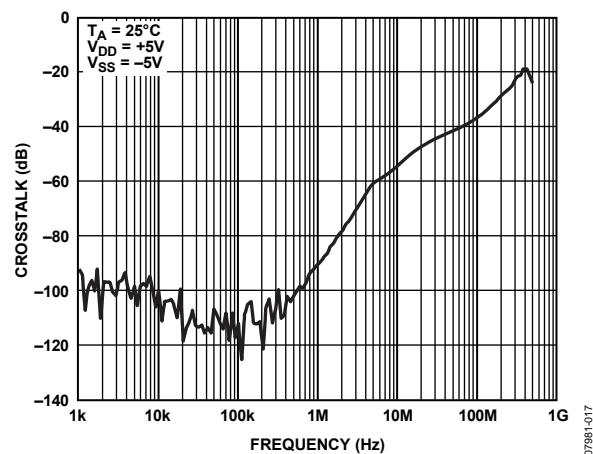


Figure 20. Crosstalk vs. Frequency

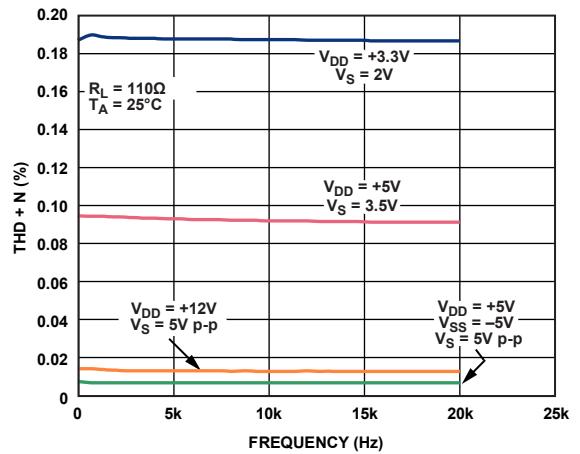


Figure 23. THD + N vs. Frequency

TEST CIRCUITS

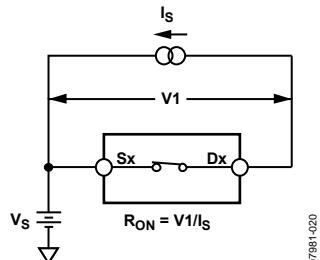
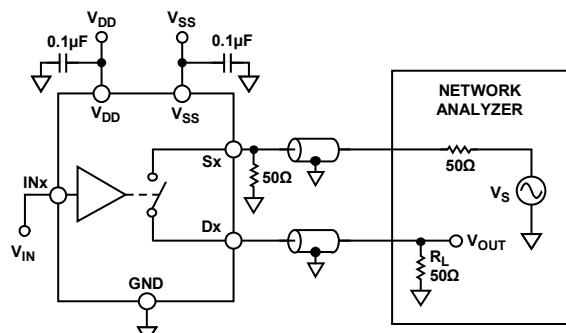


Figure 24. On Resistance

07981-020



$$\text{OFF ISOLATION} = 20 \log \frac{V_{OUT}}{V_S}$$

07981-026

Figure 27. Off Isolation

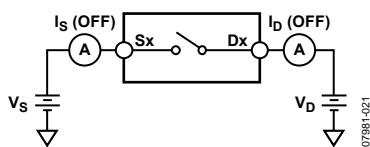
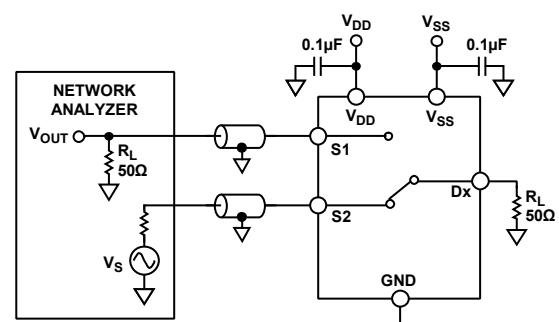


Figure 25. Off Leakage

07981-021



$$\text{CHANNEL-TO-CHANNEL CROSSTALK} = 20 \log \frac{V_{OUT}}{V_S}$$

07981-027

Figure 28. Channel-to-Channel Crosstalk

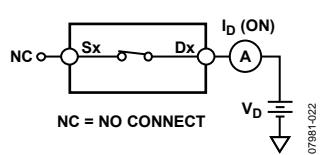
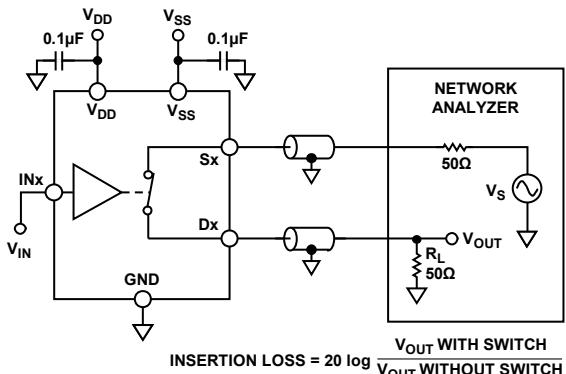


Figure 26. On Leakage

07981-022



$$\text{INSERTION LOSS} = 20 \log \frac{V_{OUT \text{ WITH SWITCH}}}{V_{OUT \text{ WITHOUT SWITCH}}}$$

07981-028

Figure 29. Bandwidth

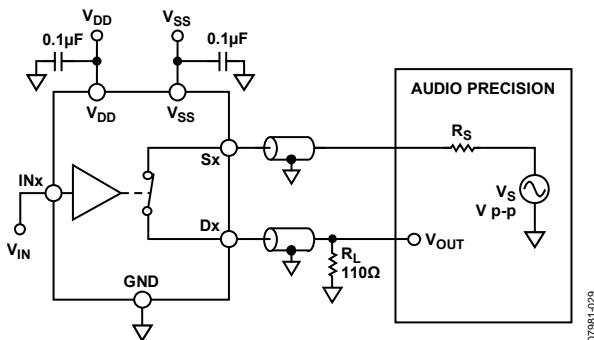


Figure 30. THD + Noise

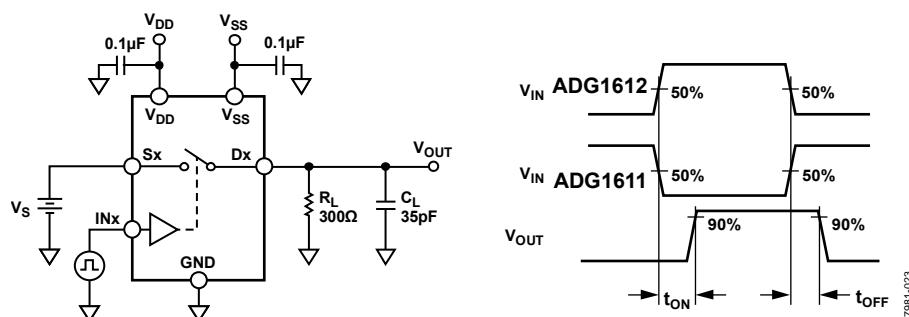


Figure 31. Switching Times

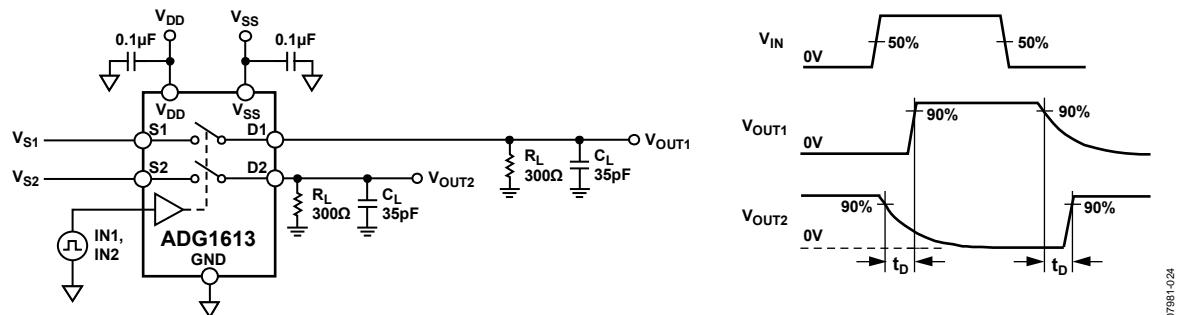


Figure 32. Break-Before-Make Time Delay

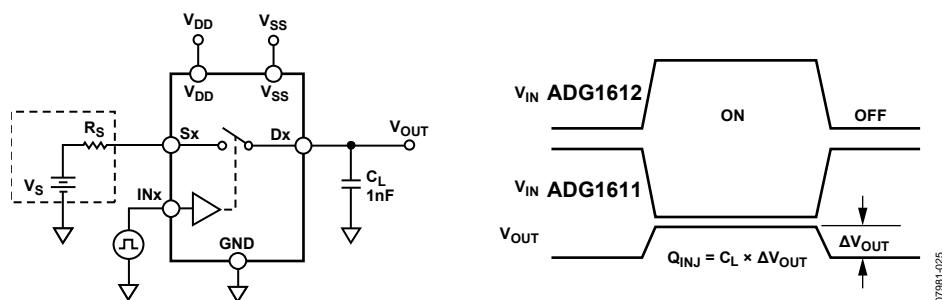


Figure 33. Charge Injection

TERMINOLOGY

I_{DD}

The positive supply current.

I_{SS}

The negative supply current.

V_D (V_S)

The analog voltage on Terminal D and Terminal S.

R_{ON}

The ohmic resistance between Terminal D and Terminal S.

R_{FLAT(ON)}

Flatness that is defined as the difference between the maximum and minimum value of on resistance measured over the specified analog signal range.

I_s (Off)

The source leakage current with the switch off.

I_d (Off)

The drain leakage current with the switch off.

I_D, I_S (On)

The channel leakage current with the switch on.

V_{INL}

The maximum input voltage for Logic 0.

V_{INH}

The minimum input voltage for Logic 1.

I_{INL} (I_{INH})

The input current of the digital input.

C_s (Off)

The off switch source capacitance, which is measured with reference to ground.

C_D (Off)

The off switch drain capacitance, which is measured with reference to ground.

C_D, C_S (On)

The on switch capacitance, which is measured with reference to ground.

C_{IN}

The digital input capacitance.

t_{ON}

The delay between applying the digital control input and the output switching on. See Figure 31.

t_{OFF}

The delay between applying the digital control input and the output switching off. See Figure 31.

Charge Injection

A measure of the glitch impulse transferred from the digital input to the analog output during switching. See Figure 33.

Off Isolation

A measure of unwanted signal coupling through an off switch. See Figure 27.

Crosstalk

A measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance. See Figure 28.

Bandwidth

The frequency at which the output is attenuated by 3 dB. See Figure 29.

On Response

The frequency response of the on switch.

Insertion Loss

The loss due to the on resistance of the switch.

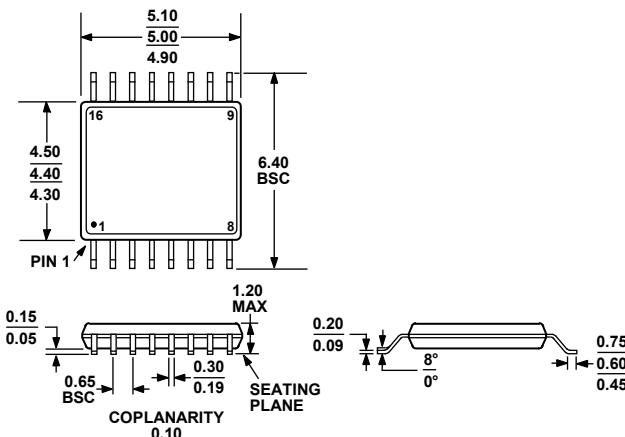
Total Harmonic Distortion + Noise (THD + N)

The ratio of the harmonic amplitude plus noise of the signal to the fundamental. See Figure 30.

AC Power Supply Rejection Ratio (ACPSRR)

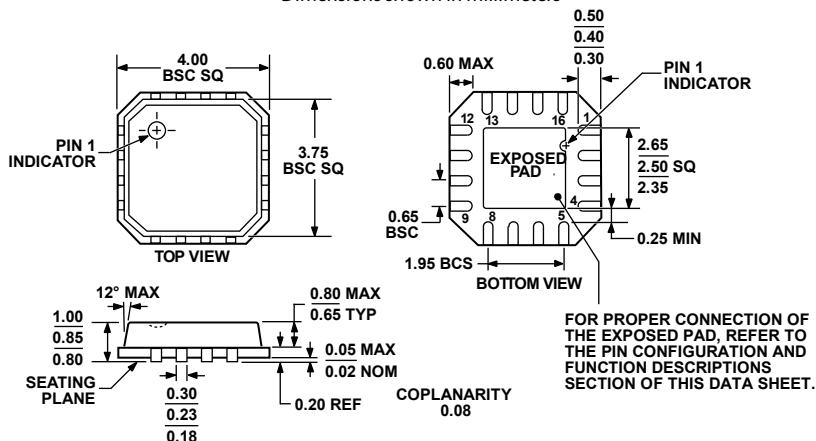
The ratio of the amplitude of signal on the output to the amplitude of the modulation. This is a measure of the ability of the part to avoid coupling noise and spurious signals that appear on the supply voltage pin to the output of the switch. The dc voltage on the device is modulated by a sine wave of 0.62 V p-p.

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-153-AB
*Figure 34. 16-Lead Thin Shrink Small Outline Package [TSSOP]
(RU-16)*

Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MO-220-VGGC.
*Figure 35. 16-Lead Lead Frame Chip Scale Package [LFCSP_VQ]
4 mm × 4 mm Body, Very Thin Quad (CP-16-13)*

Dimensions shown in millimeters

031006-A

ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Package Option
ADG1611BRUZ	-40°C to +125°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
ADG1611BRUZ-REEL	-40°C to +125°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
ADG1611BRUZ-REEL7	-40°C to +125°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
ADG1611BCPZ-REEL	-40°C to +125°C	16-Lead Lead Frame Chip Scale Package [LFCSP_VQ]	CP-16-13
ADG1611BCPZ-REEL7	-40°C to +125°C	16-Lead Lead Frame Chip Scale Package [LFCSP_VQ]	CP-16-13
ADG1612BRUZ	-40°C to +125°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
ADG1612BRUZ-REEL	-40°C to +125°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
ADG1612BRUZ-REEL7	-40°C to +125°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
ADG1612BCPZ-REEL	-40°C to +125°C	16-Lead Lead Frame Chip Scale Package [LFCSP_VQ]	CP-16-13
ADG1612BCPZ-REEL7	-40°C to +125°C	16-Lead Lead Frame Chip Scale Package [LFCSP_VQ]	CP-16-13
ADG1613BRUZ	-40°C to +125°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
ADG1613BRUZ-REEL	-40°C to +125°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
ADG1613BRUZ-REEL7	-40°C to +125°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
ADG1613BCPZ-REEL	-40°C to +125°C	16-Lead Lead Frame Chip Scale Package [LFCSP_VQ]	CP-16-13
ADG1613BCPZ-REEL7	-40°C to +125°C	16-Lead Lead Frame Chip Scale Package [LFCSP_VQ]	CP-16-13

¹ Z = RoHS Compliant Part.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помошь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помошь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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